

SOT1956-1

XQFN16, plastic, extremely thin quad flat package; no leads;
16 terminals; 0.4 mm pitch, 2.2 mm x 2.8 mm x 0.50 mm body

7 December 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN16
Package type industry code	XQFN16
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-12-2017
Manufacturer package code	SOT1956-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	2.2	-	mm
E	package width	-	-	2.8	-	mm
A	seated height	-	-	0.5	-	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	A/A



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2. Package outline

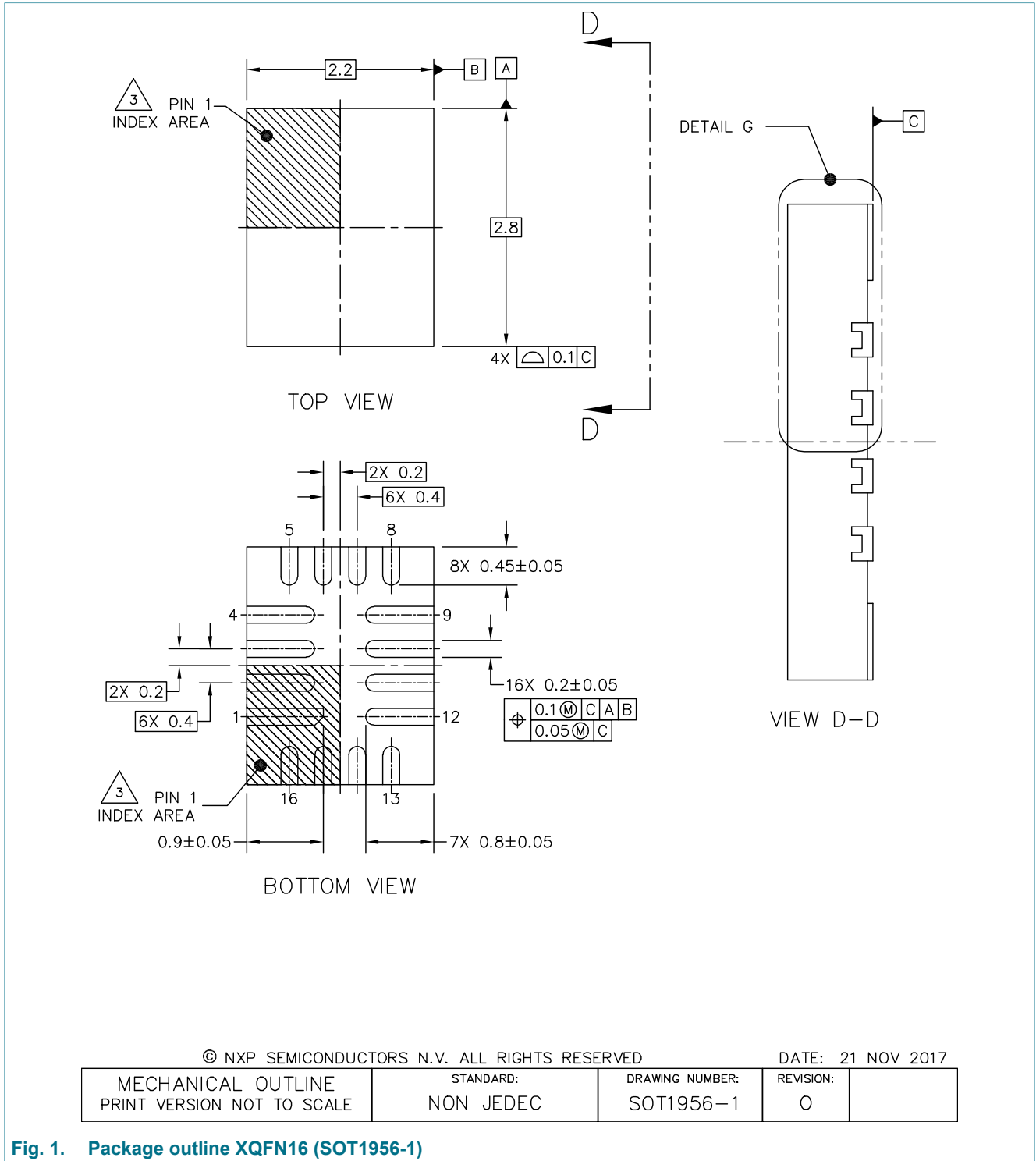
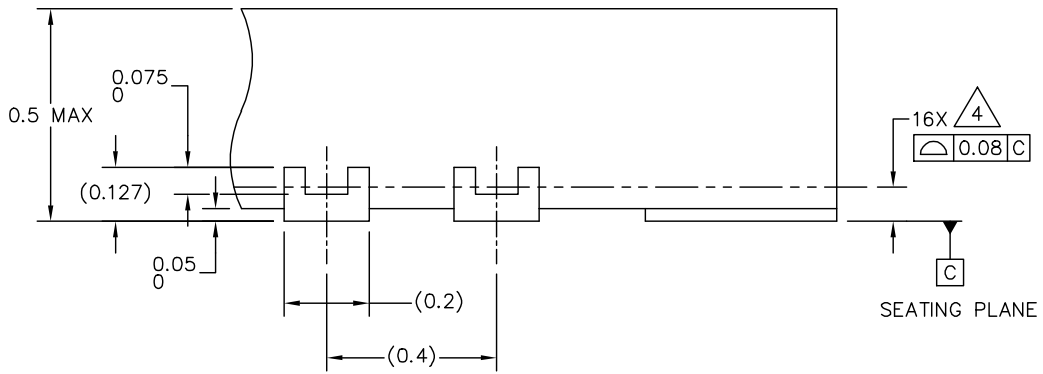


Fig. 1. Package outline XQFN16 (SOT1956-1)

XQFN16, plastic, extremely thin quad flat package; no leads; 16 terminals; 0.4 mm pitch, 2.2 mm x 2.8 mm x 0.50 mm body



DETAIL G
VIEW ROTATED 90° CW

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Fig. 2. Package outline dt1 XQFN16 (SOT1956-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3.  PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4.  COPLANARITY APPLIES TO LEADS.

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Fig. 3. Package outline note XQFN16 (SOT1956-1)

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3. Soldering

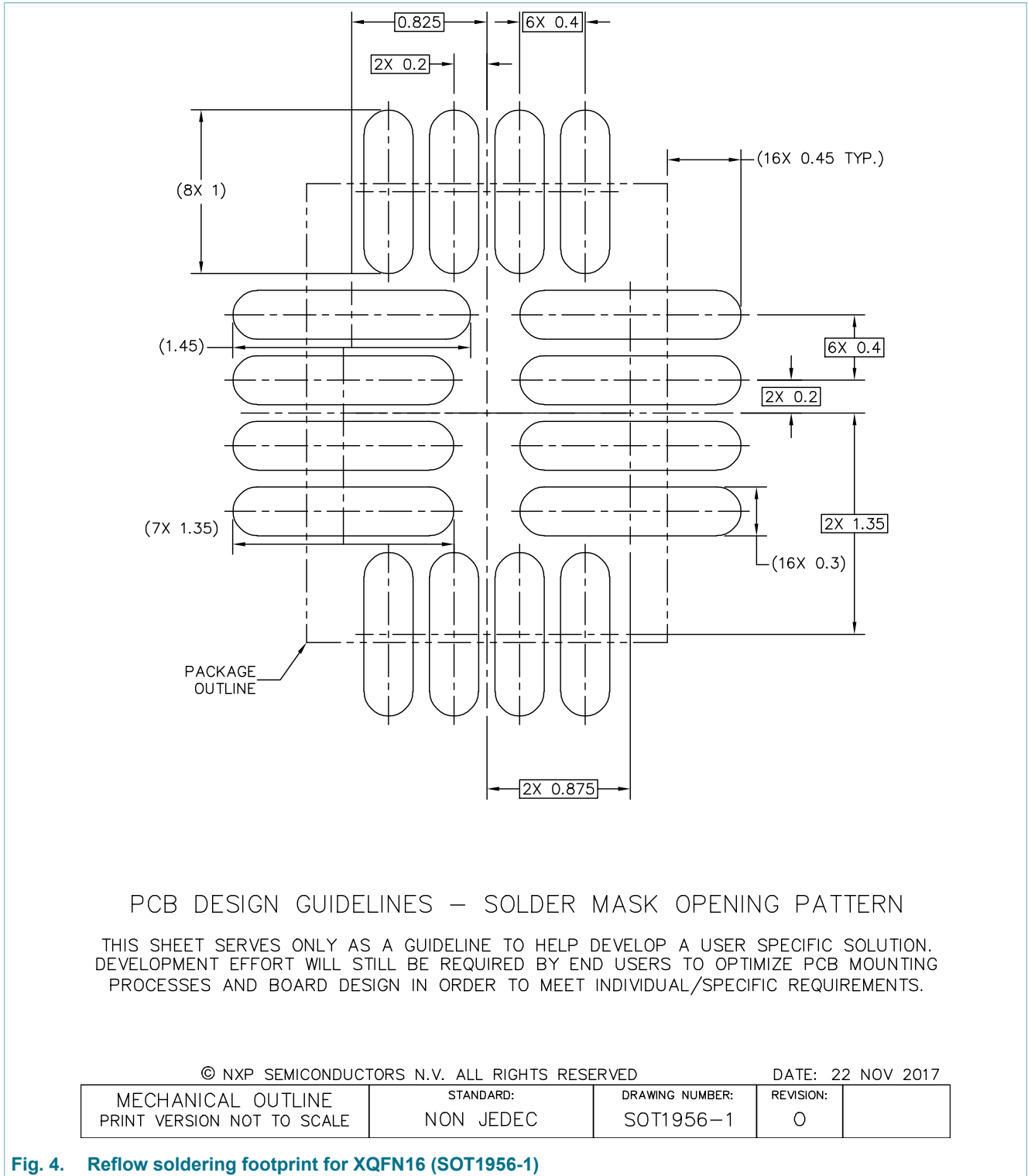
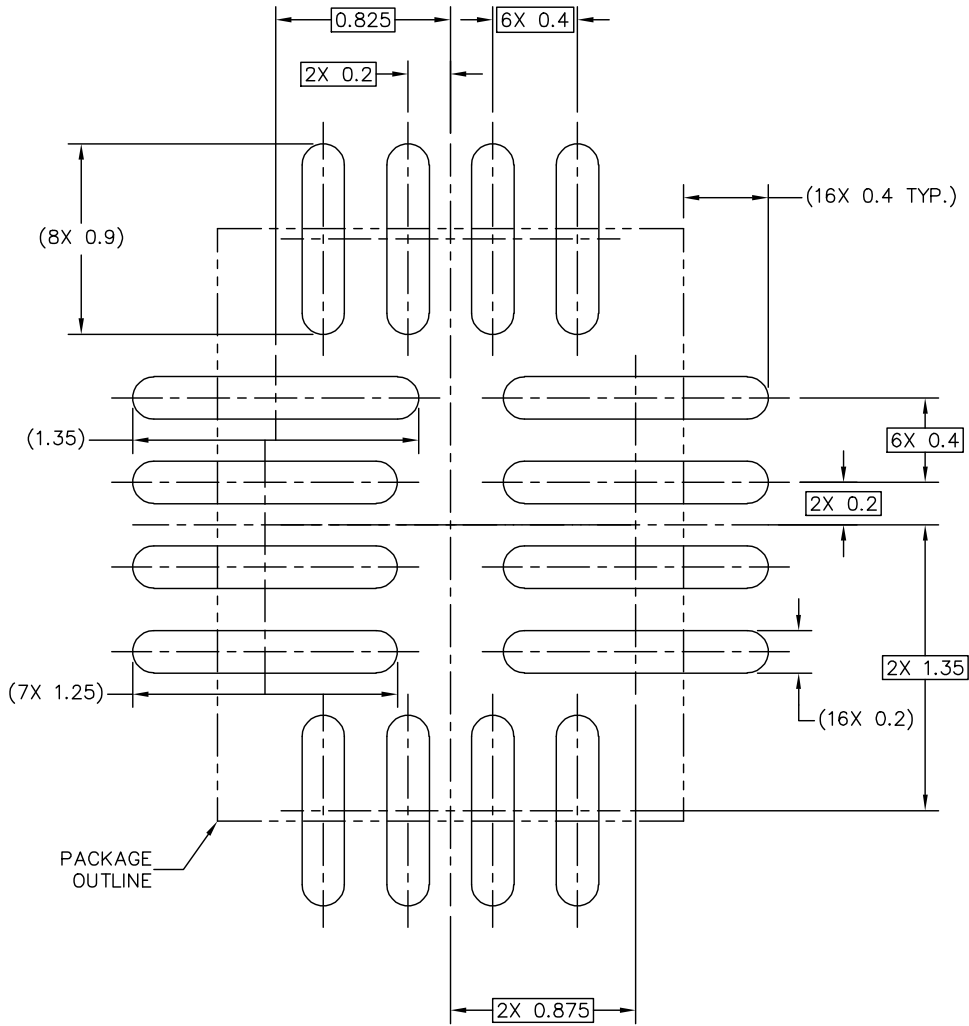


Fig. 4. Reflow soldering footprint for XQFN16 (SOT1956-1)

XQFN16, plastic, extremely thin quad flat package; no leads; 16 terminals; 0.4 mm pitch, 2.2 mm x 2.8 mm x 0.50 mm body



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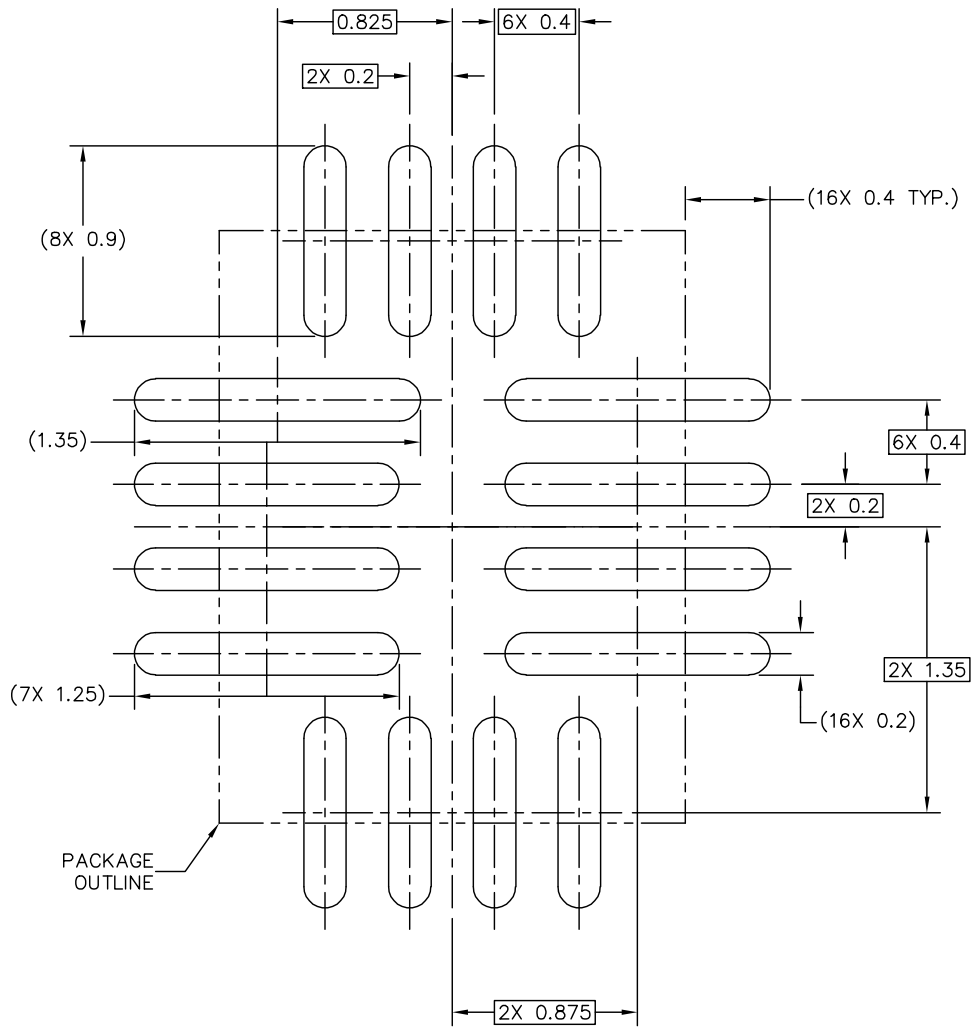
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Fig. 5. Reflow soldering footprint part2 for XQFN16 (SOT1956-1)

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RECOMMENDED STENCIL THICKNESS 0.1

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Fig. 6. Reflow soldering footprint part3 for XQFN16 (SOT1956-1)

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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